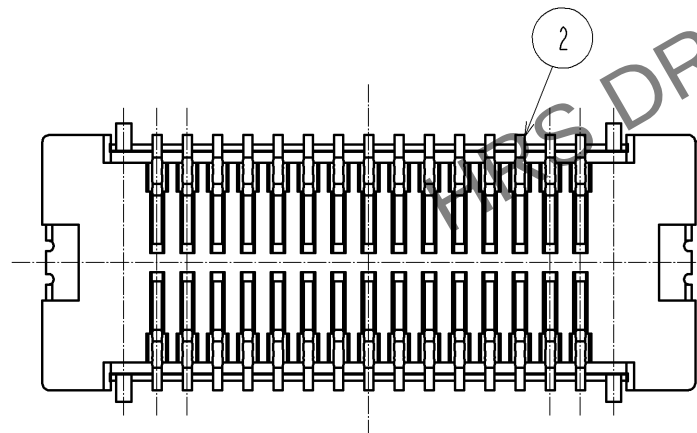
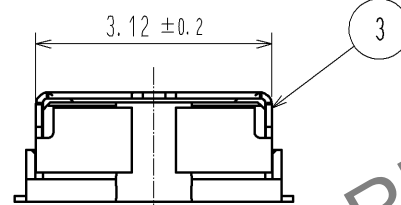
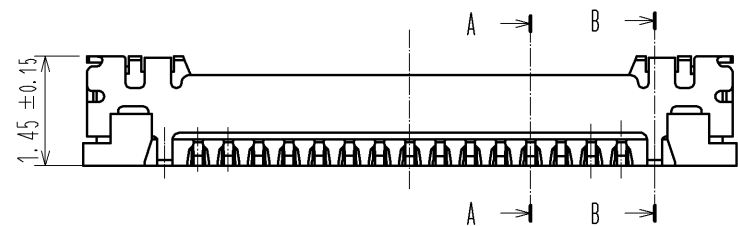
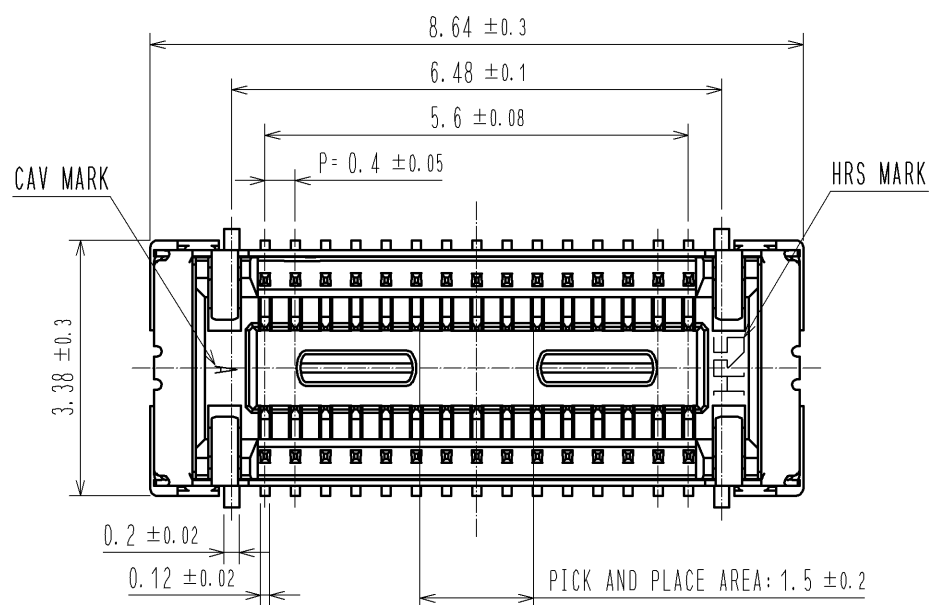
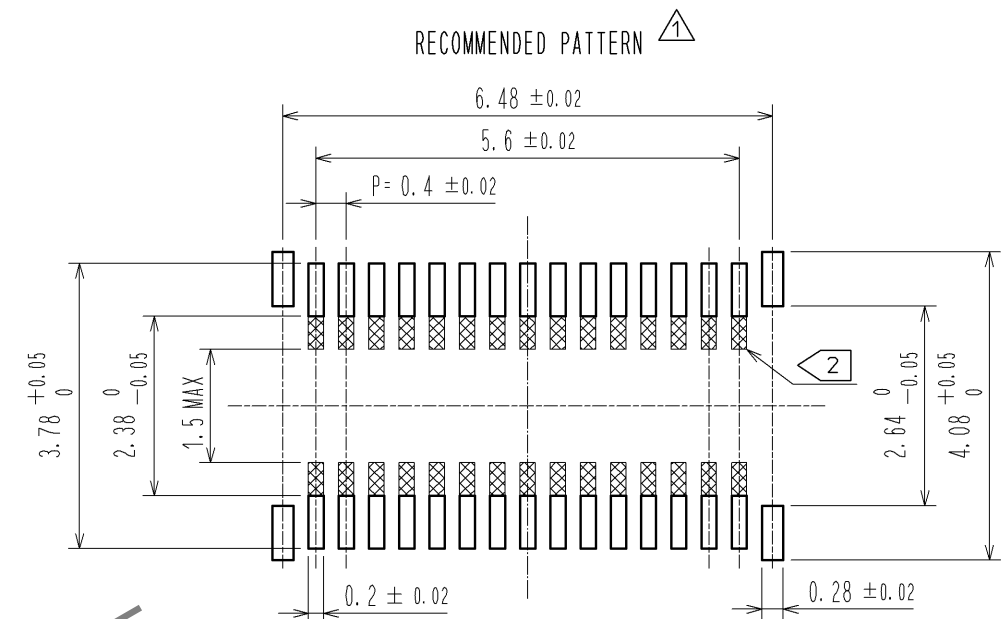
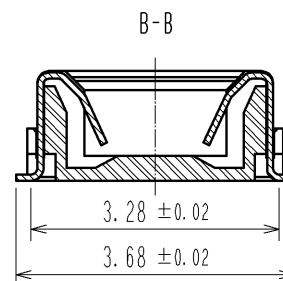
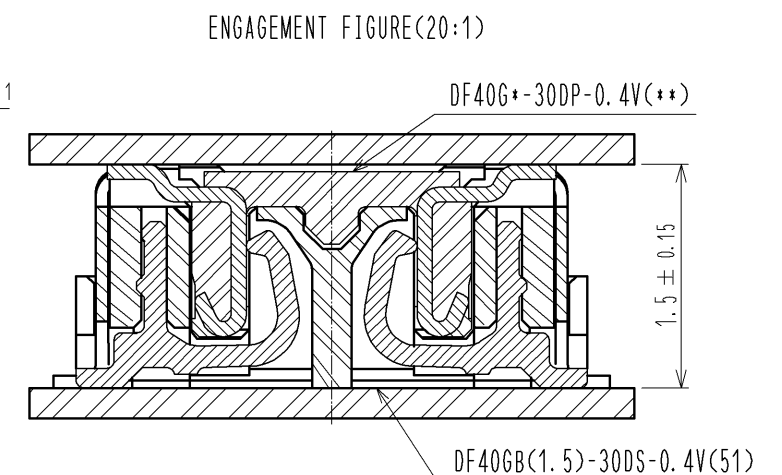
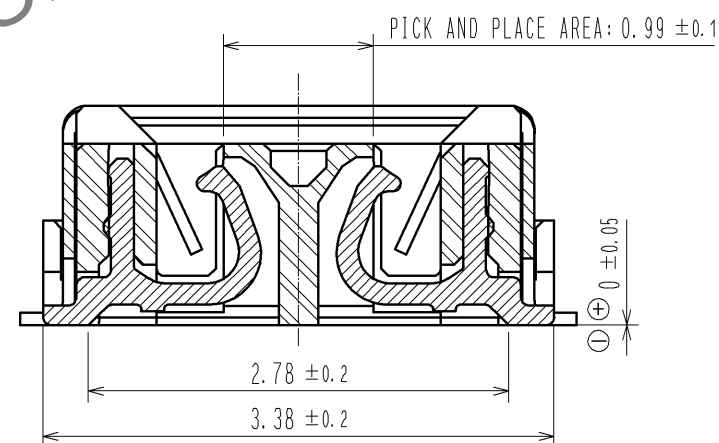




NOTES 1. ALL LEADS METAL FITTINGS CO-PLANARITY SHALL BE 0.1mm MAX.
2  IS NON-CONDUCTIVE AREA.



RECOMMENDED METAL MASK THICKNESS:120 μ m
RECOMMENDED MASK OPENING RATIO:80% FOR LEAD PAD



				7	PS	CLEAR(REINFORCEMENT COLLAR)
				6	PS	BLACK(PLASTIC REEL)
				5	POLYESTER	CLEAR(COVER TAPE)
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.05μm MIN		4	PS	CLEAR(EMBOSSED CARRIER TAPE)
		SMT LEAD:GOLD 0.05μm MIN		3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.05μm MIN
		UNDERPLATING:NICKEL 1μm MIN				SMT LEAD:GOLD 0.05μm MIN
1	LCP	BLACK, UL94V-0				UNDERPLATING:NICKEL 1μm MIN
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS

UNITS mm		SCALE 10 : 1		COUNT 1	DESCRIPTION OF REVISIONS DIS-H-008439	DESIGNED TY. YAMASAKI	CHECKED TS. MIYAZAKI	DATE 14. 01. 17
 HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA		13. 01. 31	DRAWING NO. EDC3-349575-02			
		CHECED : TS. MIYAZAKI		13. 01. 31	PART NO. DF40GB<1. 5>-30DS-0. 4V<51>			
		DESIGNED : TY. YAMASAKI		13. 01. 30	CODE NO. CL684-4198-4-51			
		DRAWN : TY. YAMASAKI		13. 01. 30	 			

